

ABSTRACT OF THE INVENTION

LAND GRID ARRAY PACKAGED DEVICE AND METHOD OF FORMING SAME

A method of packaging an integrated circuit die (12) includes the steps of providing a foil sheet (30) and forming a layer of solder (32) on a first side of the foil sheet. A first side of the integrated circuit die is attached to the solder on the foil sheet. The first side of the die has a layer of metal (34) on it and a second, opposing side of the die includes bonding pads (14). The bonding pads are electrically connected to the solder on the foil sheet with wires (16). The die, the electrical connections, and the first side of the foil sheet are encapsulated with a mold compound (20). The foil sheet is separated from the die and the wires, which forms a packaged integrated circuit (10).